# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**
[List multiple models if applicable.]

HP Split 13 x 2 Notebook PC

## Purpose
The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Main/B, Touch pad, USB/B, HDMI/B</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Slate Baterry, Dock Battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 ScrewDriver</td>
<td></td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Separate Slate side and Dock side
2. For Slate module:
3. Dis-fasten Slate module Bezel trim screw*2(M2.0*3.5)
4. Disassemble LCD cover
5. Pull out battery cable
6. Dis-fasten screw*40(M2.0*3.5, M2.0*2.5, M2.0*2)
7. Disassemble Docking FPC
8. Disassemble Docking cable
9. Disassemble Battery
10. Pull out Micro SD FFC
11. Disassemble Micro SD/Board
12. Disassemble Audio/Board
13. Disassemble Home Led/Board
14. Disassemble Bezel trim
15. Pull out Fan FPC
16. Disassemble Thermal module
17. Pull out Camera cable
18. Pull out LCD cable
19. Pull out Volume/Board FFC
20. Pull out Power/Board FFC
21. Pull out Antenna cable*2
22. Pull out TS FFC
23. Pull out TS/Board FPC
24. Disassemble TS/Board
25. Disassemble Power/Board
26. Disassemble Volume/Board and Vibrator
27. Disassemble Wlan Card
28. Disassemble SSD card
29. Disassemble Ram module
30. Disassemble Frame
31. Disassemble Main/Board
32. Disassemble Speaker(L&R)
33. Disassemble Antenna module
34. For Dock Module:
35. Pull out Rubber from Base*2

PSG instructions for this template are available at EL-MF877-01
36. Dis-fasten Bottom Base screw*6(M2.5*5, M2.5*4)
37. Disassemble Base
38. Dis-fasten hinge screw*8(M2.5*5, L&R)
39. Disassemble Hinge Assy
40. Dis-fasten battery screw*6(M2.5*5)
41. Pull out Battery cable and Disassemble Battery
42. Dis-fasten HDD screw*3(M2.5*4)
43. Pull out HDD cale
44. Disassemble HDD Assy
45. Dis-fasten HDD Assy screw*4(M3.0*3.5)
46. Dis-fasten Toch pad screw*2(M2.0*2.0)
47. Pull out TP FFC
48. Disassemble Touch pad module
49. Dis-fasten Dummy weight screw*1(M2.5*2.5)
50. Disassemble Dummy Weight
51. Dis-fasten USB/B & HDMI/B screw*3(M2.5*4)
52. Pull out KeyBoard FPC
53. Disassemble USB/B & HDMI/B
54. Pull out PCB Link FFC
55. For Hinge Assy :
56. Pull out Hinge screw mylar
57. Dis-fasten hinge screw*4(M2.5*8)
58. Disassemble Hinge cap
59. Dis-fasten screw*4(M2.0*4)
60. Disassemble Hinge sub assy
61. Dis-fasten screw*4(M2.0*4, L&R)
62. Disassemble Hinge bkt
63. Dis-fasten screw*3 on latch
64. Disassemble hinge Latch

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. 

2. 

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